



Product/Process Change Notice - PCN 21_0021 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Correction of Package Outline Drawing for Select HMC Products in Carsem in the 8L SOIC E-Pad Package

Publication Date: 29-Jan-2021

Effectivity Date: 29-Jan-2021 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:
Initial Release.

Description Of Change:

Package outline drawing in the product data sheet is being revised from standard lead stand-off height (4-10 mils) to lower lead stand-off height (0-5 mils)

Reason For Change:

Original stand-off height prior to product transfer to Carsem in Sept 2019, was 0-5 mils. The affected HMC parts listed in this PCN were produced in Carsem using the standard stand-off height (4-10 mils) since the transfer. ADI is rectifying the error in stand-off height specification to mitigate the risk to customers who may be soldering the E-pad onto the board.

Impact of the change (positive or negative) on fit, form, function & reliability:

Lower lead stand-off height will have positive impact to customers' E-pad board mounting quality.

Product Identification *(this section will describe how to identify the changed material)*

Parts with low stand-off will be identified with a cut-off date code.

Summary of Supporting Information:

No additional qualification required.

Supporting Documents

Attachment 1: Type: Detailed Change Description

ADI_PCN_21_0021_Rev_-_8L SOIC E-pad POD revision details.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:
PCN_Americas@analog.com

Europe:
PCN_Europe@analog.com

Japan:
PCN_Japan@analog.com

Rest of Asia:
PCN_ROA@analog.com

Appendix A - Affected ADI Models**Added Parts On This Revision - Product Family / Model Number (18)**

HMC361G / HMC361S8G	HMC361G / HMC361S8GE	HMC361G / HMC361S8GETR	HMC361G / HMC361S8GTR	HMC362G / HMC362S8G
HMC362G / HMC362S8GE	HMC362G / HMC362S8GETR	HMC362G / HMC362S8GTR	HMC363G / HMC363S8G	HMC363G / HMC363S8GE
HMC363G / HMC363S8GETR	HMC363G / HMC363S8GTR	HMC365G / HMC365S8G	HMC365G / HMC365S8GE	HMC365G / HMC365S8GETR
HMC365G / HMC365S8GTR	HMC754 / HMC754S8GE	HMC754 / HMC754S8GETR		

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	29-Jan-2021	29-Jan-2021	Initial Release.

Analog Devices, Inc.

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